Jun.28.2002

Heat-Resistant Silicone Polyimide Adhesive Tape "TRM-6250L"

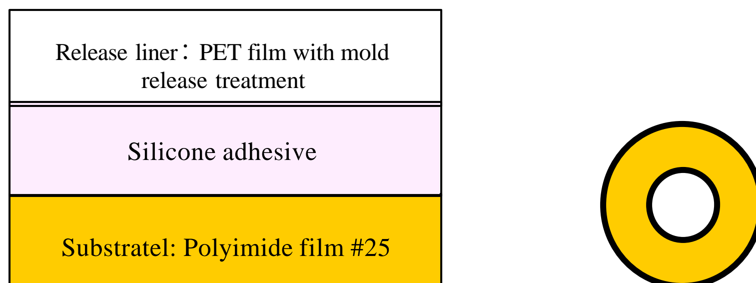
《Features》
・Polyimide backing with excellent heat resistance
・Liner is applied to the product for better quality control.

《Applications》
・Heat resistance masking for electronic components manufacturing process
・Temporary fixation for electronic components manufacturing process.
etc.

《General Characteristics》

ITEM	UNIT	TRM-6250L
Total thickness (without liner)	mm	0.030
Substrate thickness		0.025
Adhesive thickness		0.005
Adhesion to stainless plate *1	N／20mm	0.53
Adhesion to Cu-L/F *1		0.81
Adhesion to NiPd-L/F *1		0.55
Separator peel force*2	N／50mm	0.04

《Configuration》



*1 Testing method (JIS Z0237)
・Conditions of application: Reciprocating a roller of 2kg at the speed of about 5 mm/sec once
・Conditions of tape peeling: Peel angle=180°, peel rate=300 mm/min

*2 Testing Method (JIS Z0237)
・Conditions of liner peeling: Peel angle=180°, peel rate=300 mm/min

Note: The numbers in the above data are typical measurements in our laboratory and not the guaranteed values.

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Heat resistance performance of TRM-6250L

Test result (Adhesive residue)

Item \ Heating time		Heating temp.: 200℃		
		30min.	60min.	90min.
TRM-6250L	To Cu-L/F	○	○	○
	To NiPd-L/F	○	○	○

《Evaluation method》
① Laminated a tape to a lead frame with a hand roller.
② Heated it at 220℃ for specified time.
③ Resin sealing: 180℃×2 min.
④ After cooling it down to room temperature, the tape was peeled off at the angle of 180° and at the speed of 300 mm/min.
Then, adhesive transfer on L/F surface was checked using a microscope (×175).
○: No adhesive residue found.
△: Adhesive residue partially found.
×: Adhesive residue overall found.

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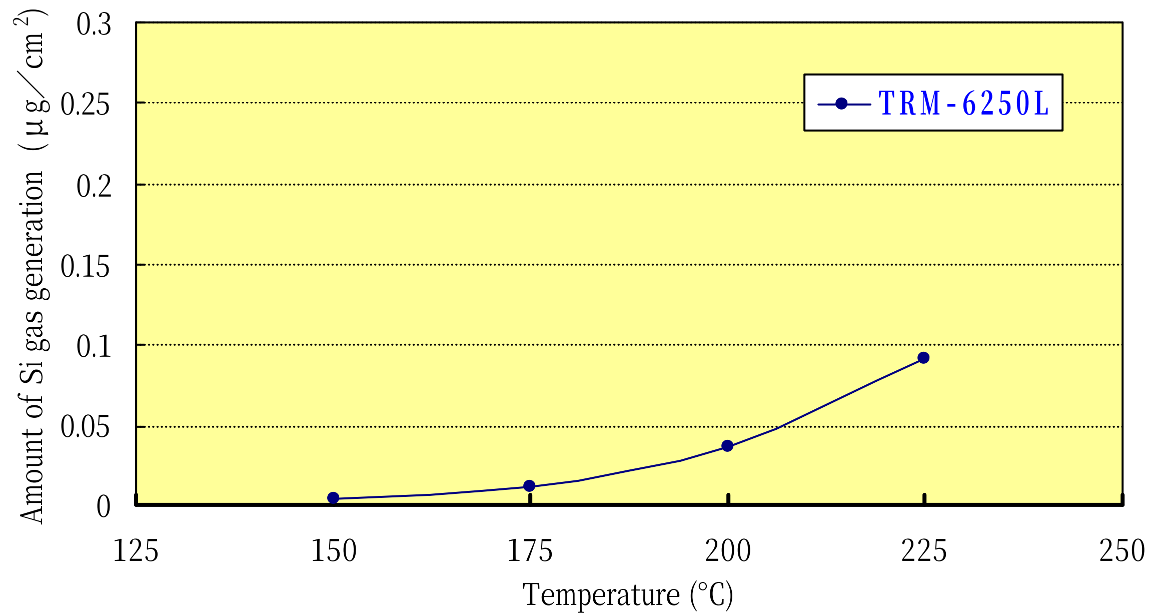
Amount of Siloxane Gas Generation from TRM-6250L



《Measuring conditions》

- Heating time: 30 min.
- Sample size: 20 cm²
- Gas chromatography
  - Column: DB-1 3 μm(0.545 mmφ ×30m)
  - Column temperature: 40℃(5 min.) ⇒ 10℃/min ⇒ 260℃(13 min.)
  - Carrier gas: He 7.9 ml/min

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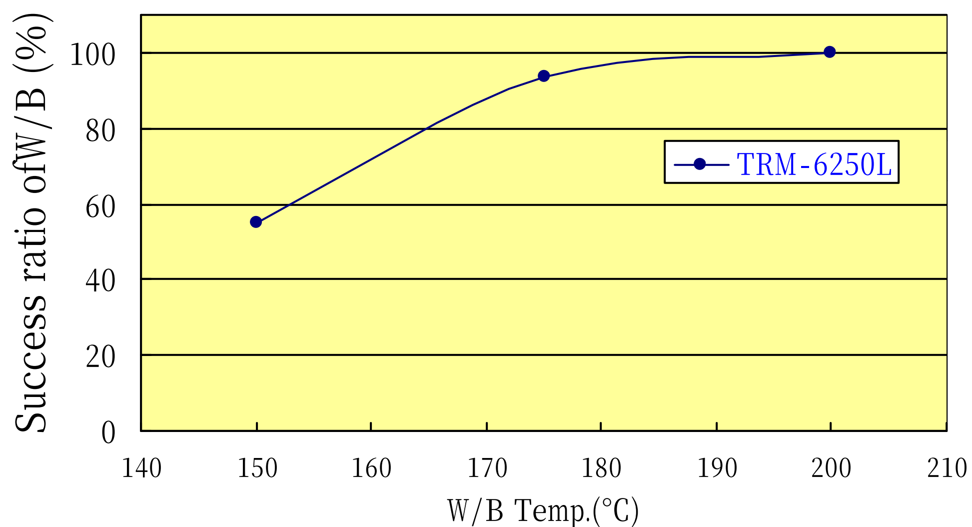
Wire Bonding Properties of TRM-6250L

Success ratio of Wire bonding



《Measuring conditions》

◆ Wire Bonder: Shinkawa UTC-300BI super (U.S.Frequency: 115kHz)

・First Ball: Bond force 80gf, U.S.Frequency 550mW, Bond Time 10ms

・Second Wedge: Bond force 80gf, U.S.Frequency 500mW, Bond Time 8ms

◆Au Wire: Tanaka GMG-25 μm

◆ L/F: Cu /Spot Ag

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